



29th 태성에스엔이 CAE Conference



Introduction to Multiscale Analysis and Examples related to PCB

Koji Yamamoto

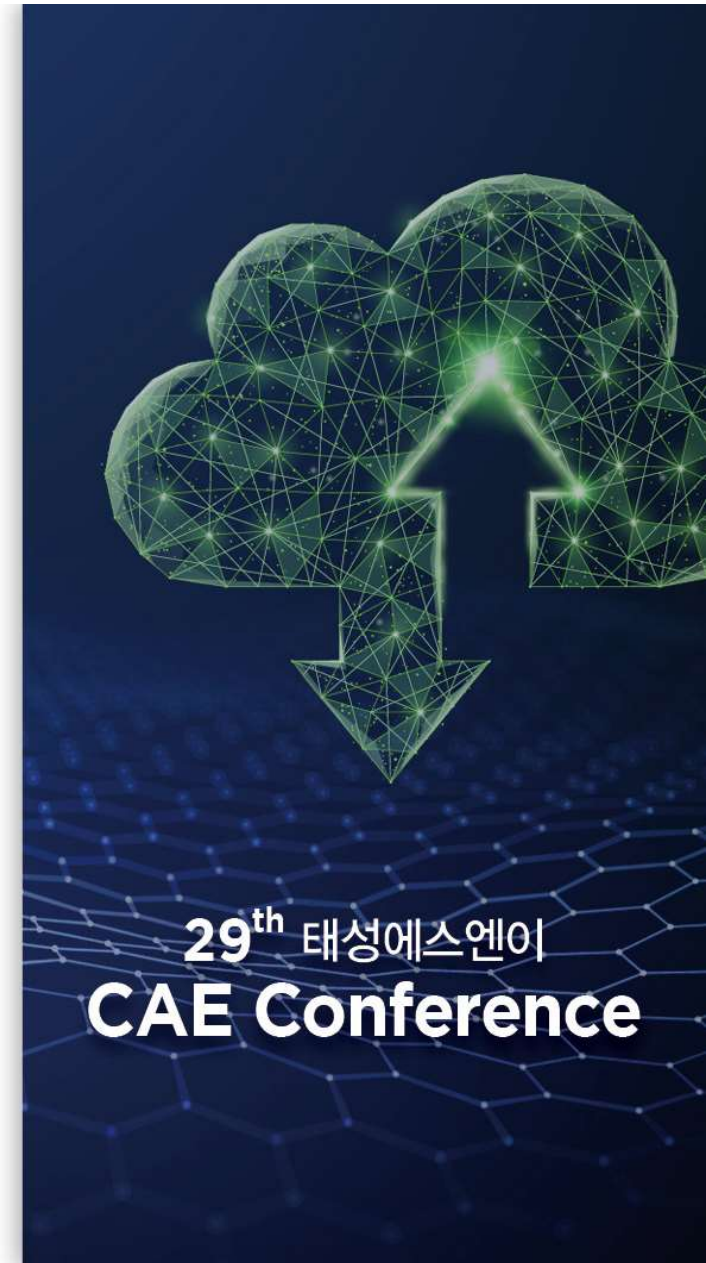
CYBERNET SYSTEMS CO., LTD.

Hyojun Ha

Taesung S&E

CONTENTS

1. Background
2. Multiscale Analysis
3. Analysis Examples
4. Summary

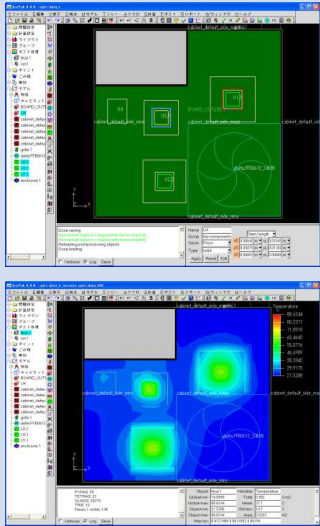
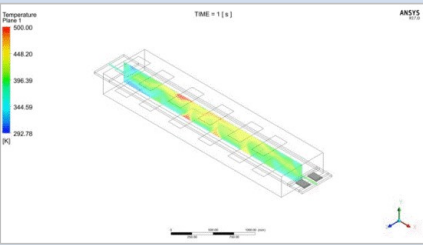
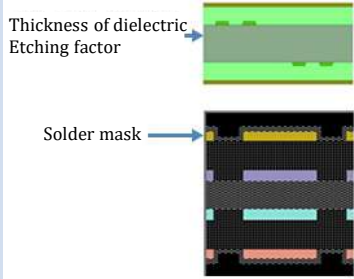
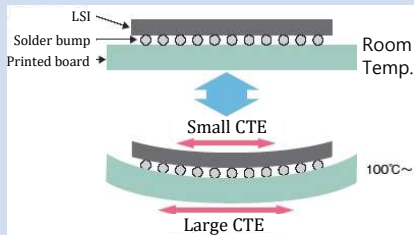
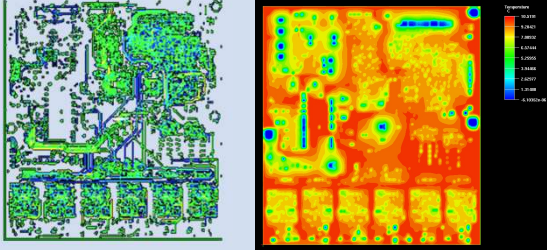
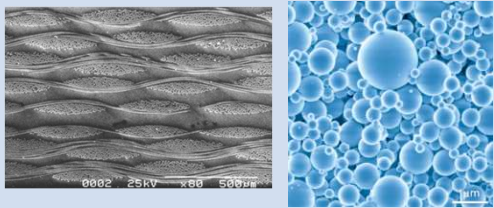


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CAE
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Background

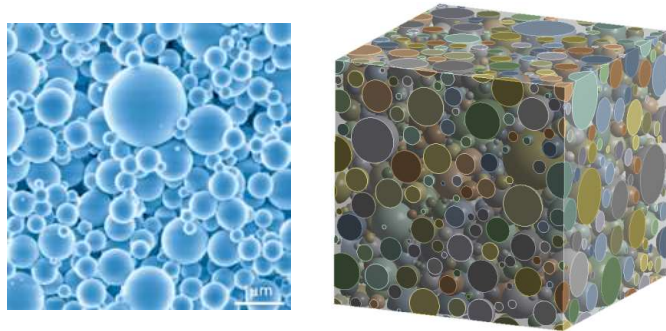
Occurrence factor of warpage in PCB

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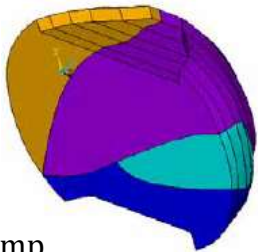
| Problem | Distributed temperature | Mismatched material constants | Non homogeneous materials |
|------------------------|---|--|--|
| Image |  <p>In operation cooling by fans or fins</p> <p>Heat generation by electronic components</p>  <p>In reflow process</p> |   |  <p>Wiring distribution</p>  <p>GFRP (FR4) Under fill</p> |
| CAE tools for analysis | <p>ANSYS Fluent ANSYS Icepack ANSYS SI wave</p> | <p>ANSYS Mechanical</p> | <p>Multiscale.Sim(CMAS) ANSYS Mechanical</p> |

PCB made by Multi Material

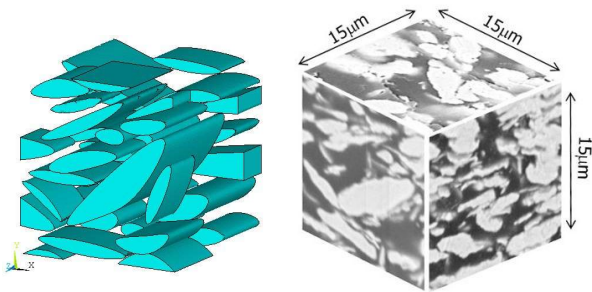
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Under fill



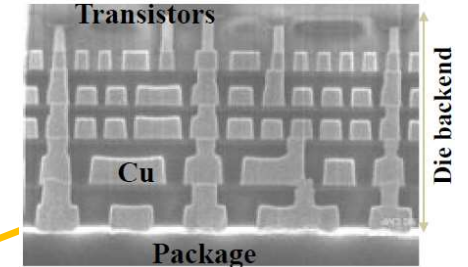
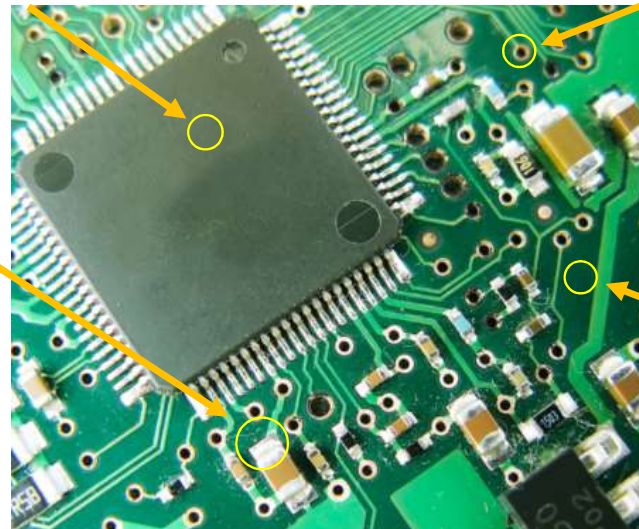
Solder bump



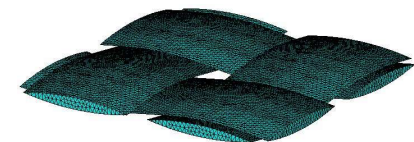
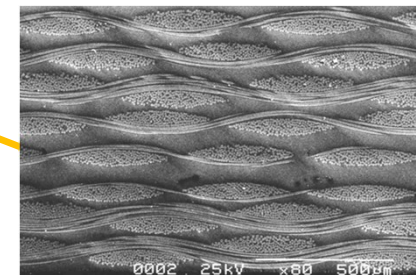
Conductive adhesive(Epoxy & Filler etc.)

PCB is constructed by many kinds of composite materials

Need an-isotropic material constants for CAE analysis



Wiring, Via etc.

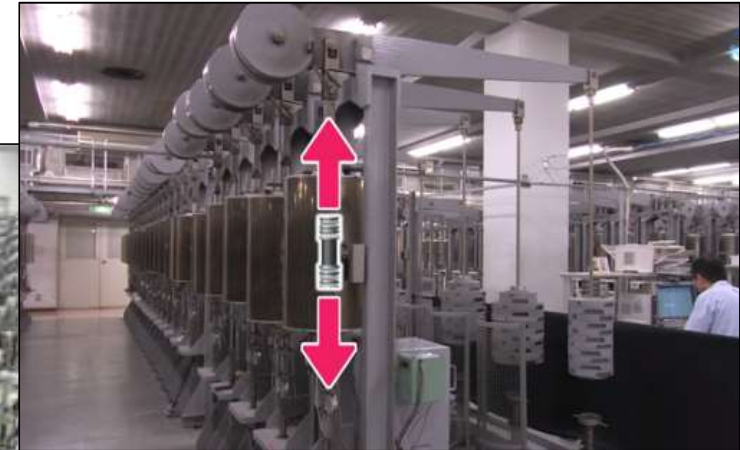


Base material (FR4)

Oppressive Material Test

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Testing just waiting earnestly for a long time



The longest record with respect
to creep testing
||
50 years

There are 380 testing machines in the
room which has 15m * 50m

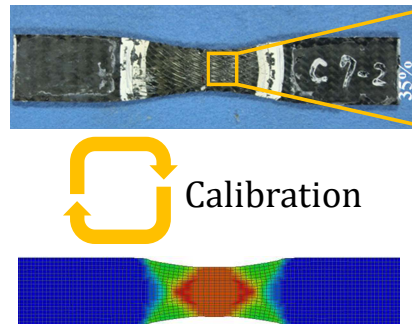
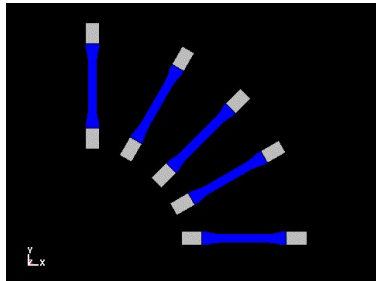
Reference) National Institute for Materials Science

<https://www.nims.go.jp/publicity/digital/movie/mov150916.html>

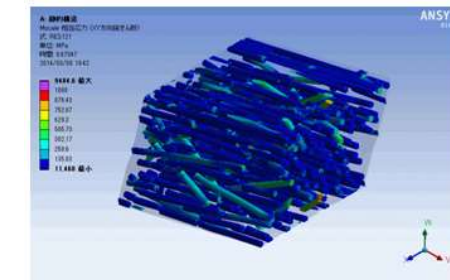
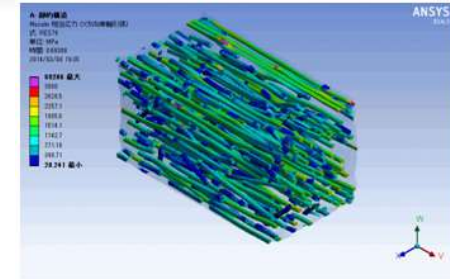
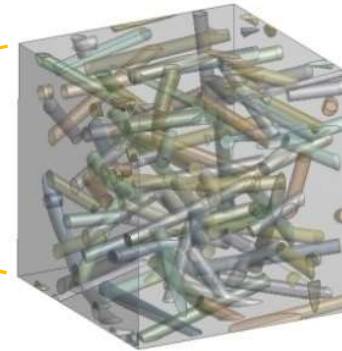
Analysis for Material Constants Identification

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- Analysis approach to identify material constants
 - Dumbbell specimen model : Reverse identification by calibration
 - Unit cell model : Evaluated definitively from analysis results



Analysis by dumbbell specimen



Analysis by unit cell specimen

| Characteristics | Dumbbell specimen | Unit Cell specimen |
|--|-------------------|-----------------------|
| Cost for model creation | ○ | △(Tends to get large) |
| Boundary conditions | ○ | △(complex) |
| Consistent with actual tests | ○ | △ |
| Executable deformation modes | × (limited) | ○ |
| Executable identification of all constants | △(limited) | ○ |

× : bad
 △ : medium
 ○ : good

Material Constants for an isotropic property

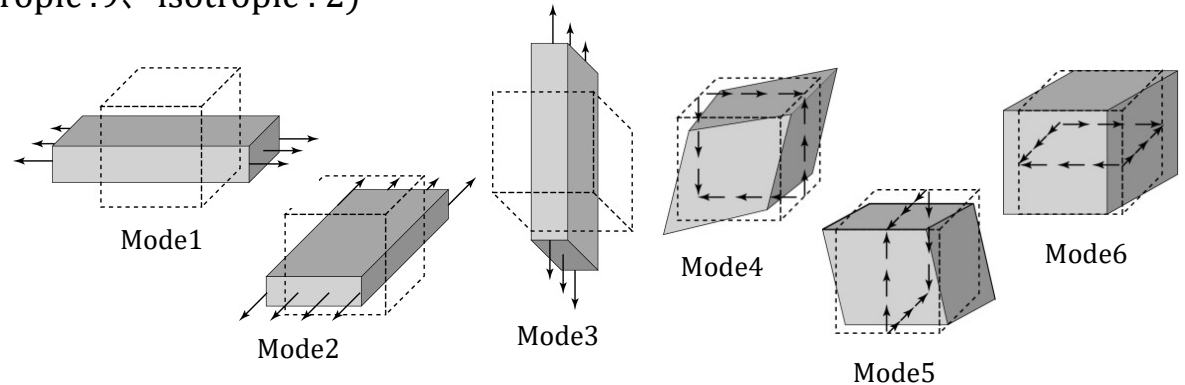
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■ Stiffness matrix for solid

Number of material constant (an isotropic:21, orthotropic:9, isotropic:2)

$$\begin{Bmatrix} \sigma_{xx} \\ \sigma_{yy} \\ \sigma_{zz} \\ \tau_{xy} \\ \tau_{yz} \\ \tau_{xz} \end{Bmatrix} = \begin{bmatrix} C_{11} & C_{12} & C_{13} & C_{14} & C_{15} & C_{16} \\ C_{21} & C_{22} & C_{23} & C_{24} & C_{25} & C_{26} \\ C_{31} & C_{32} & C_{33} & C_{34} & C_{35} & C_{36} \\ C_{41} & C_{42} & C_{43} & C_{44} & C_{45} & C_{46} \\ C_{51} & C_{52} & C_{53} & C_{54} & C_{55} & C_{56} \\ C_{61} & C_{62} & C_{63} & C_{64} & C_{65} & C_{66} \end{bmatrix} \begin{Bmatrix} \epsilon_{xx} \\ \epsilon_{yy} \\ \epsilon_{zz} \\ \epsilon_{xy} \\ \epsilon_{yz} \\ \epsilon_{xz} \end{Bmatrix}$$

Unknown Parameters

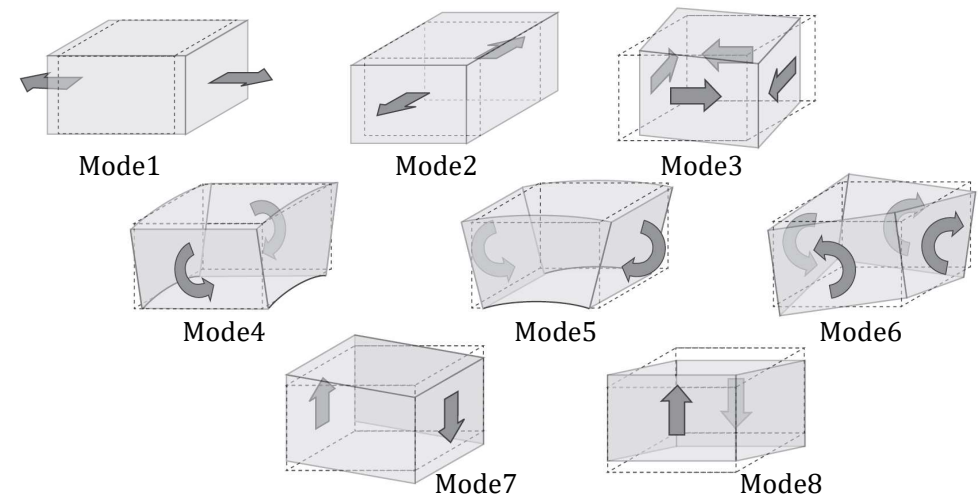


■ Stiffness matrix for shell

Number of material constant : 21

$$\begin{Bmatrix} N_{11} \\ N_{22} \\ N_{12} \\ M_{11} \\ M_{22} \\ M_{12} \\ S_{23} \\ S_{13} \end{Bmatrix} = \begin{bmatrix} A_{11} & A_{12} & A_{13} & B_{11} & B_{21} & B_{31} & 0 & 0 \\ A_{21} & A_{22} & A_{23} & B_{12} & B_{22} & B_{32} & 0 & 0 \\ A_{31} & A_{32} & A_{33} & B_{13} & B_{23} & B_{33} & 0 & 0 \\ B_{11} & B_{12} & B_{13} & D_{11} & D_{12} & D_{13} & 0 & 0 \\ B_{21} & B_{22} & B_{23} & D_{21} & D_{22} & D_{23} & 0 & 0 \\ B_{31} & B_{32} & B_{33} & D_{31} & D_{32} & D_{33} & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & E_{11} & E_{12} \\ 0 & 0 & 0 & 0 & 0 & 0 & E_{21} & E_{22} \end{bmatrix} \begin{Bmatrix} e_{11} \\ e_{22} \\ e_{12} \\ \kappa_{11} \\ \kappa_{22} \\ \kappa_{12} \\ g_{23} \\ g_{13} \end{Bmatrix}$$

Unknown Parameters



Resultant stress

Introduction of Multiscale Analysis

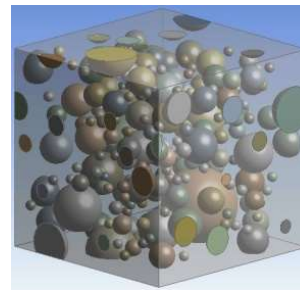
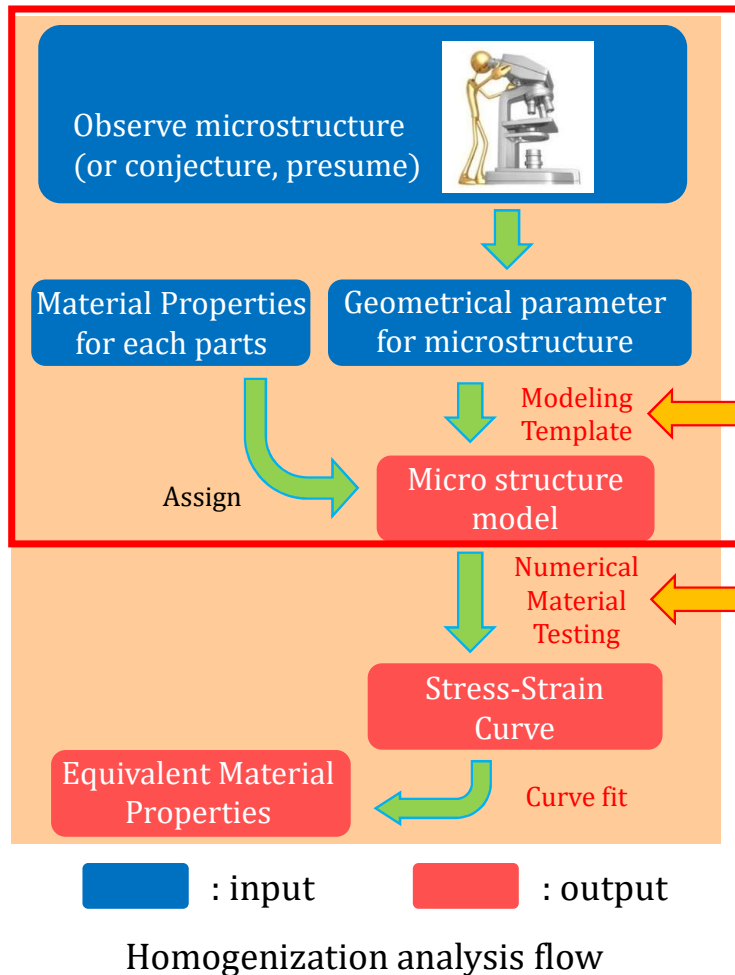
Homogenization analysis using Multiscale.Sim

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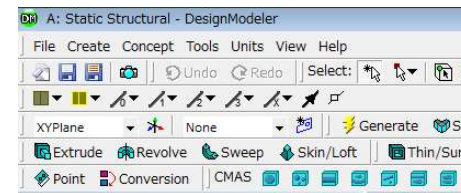


What is Multiscale.Sim?

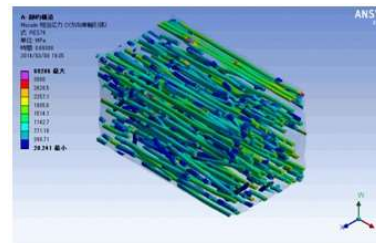
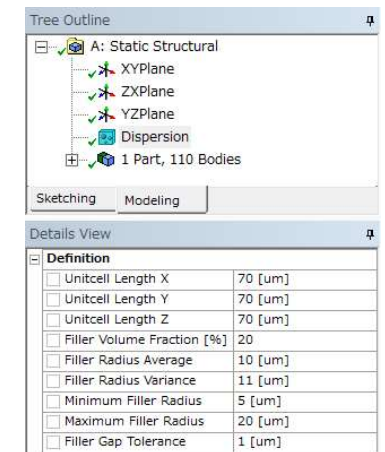
Add in tool to homogenization analysis on ANSYS Workbench



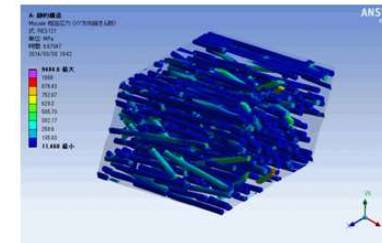
Model for microstructure



Modeling Template GUI is integrated to Design Modeler

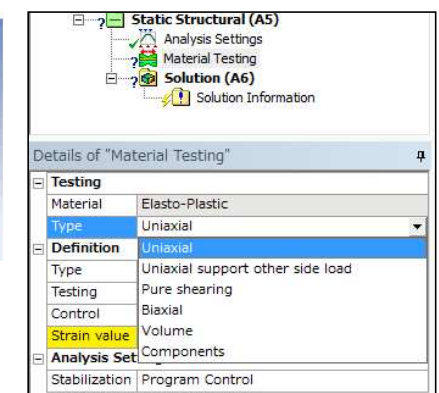


Uniaxial tension for x dir.



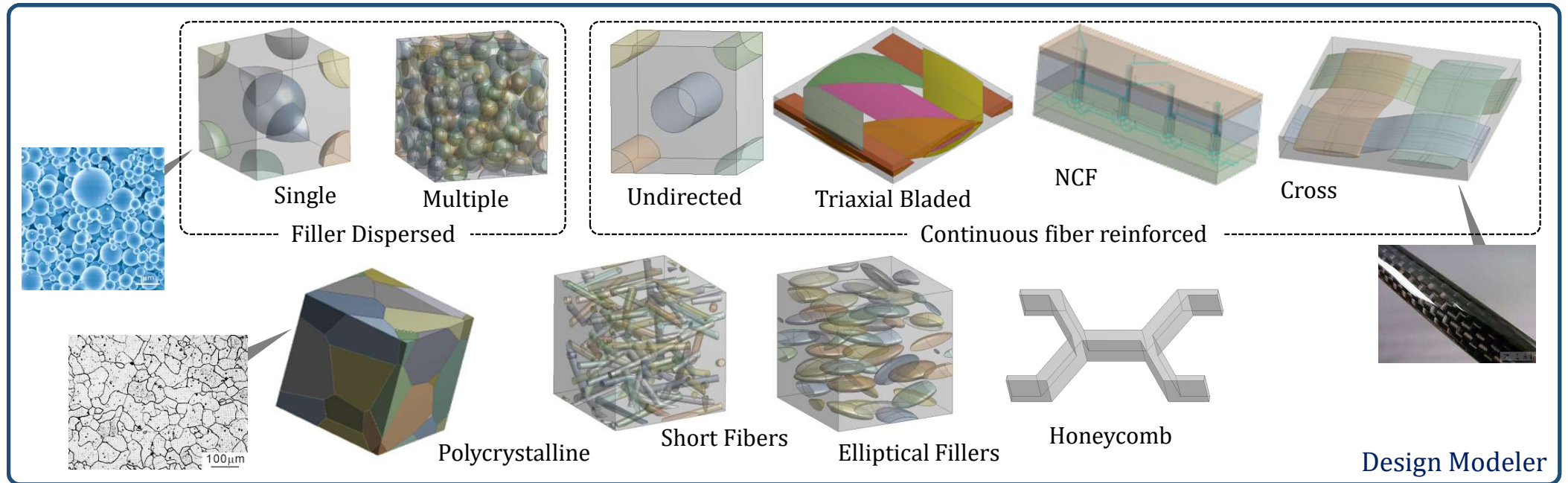
Pure shearing for xy dir.

Material test for any deformation mode and loading history

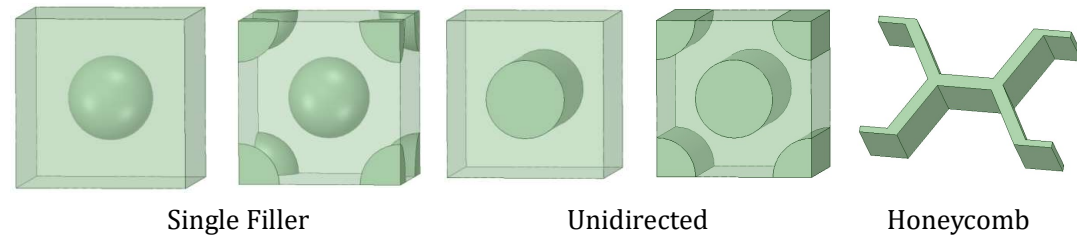


Templates for Micro Model Creation

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Migration



SpaceClaim

Representative microstructure which can be made by Multiscale.Sim

Multiscale.Sim

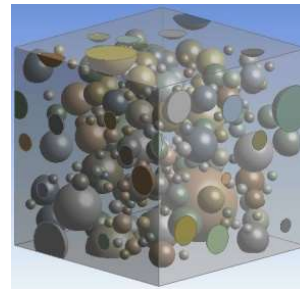
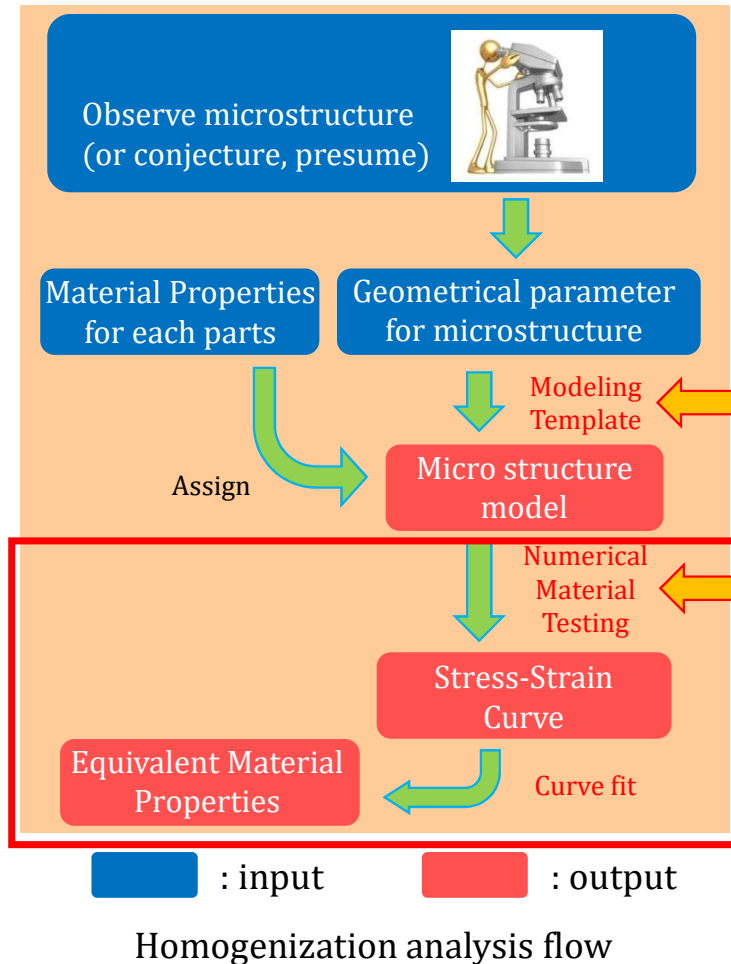
Homogenization analysis using Multiscale.Sim

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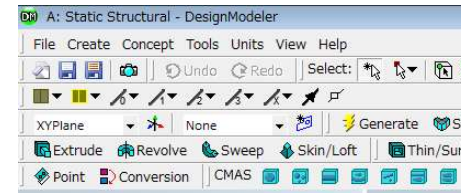


What is Multiscale.Sim?

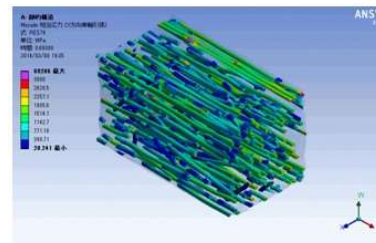
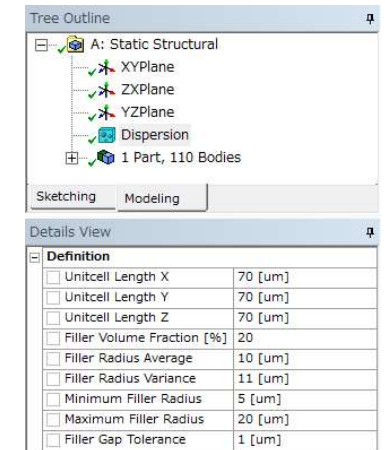
Add in tool to homogenization analysis on ANSYS Workbench



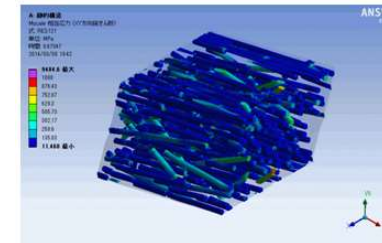
Model for microstructure



Modeling Template GUI is integrated to Design Modeler

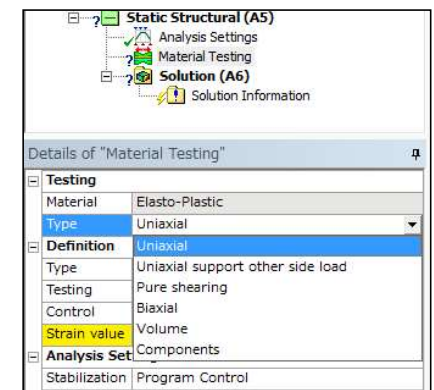


Uniaxial tension for x dir.



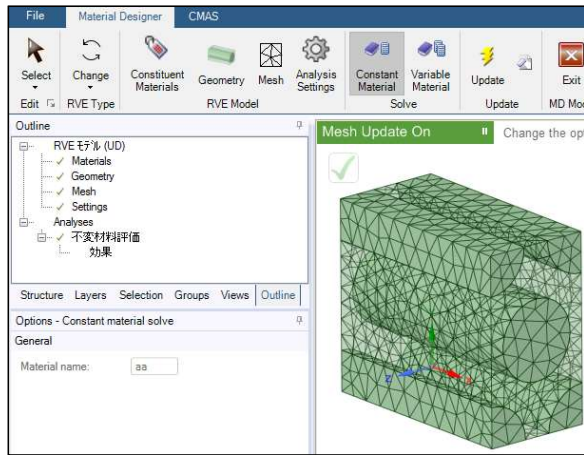
Pure shearing for xy dir.

Material test for any deformation mode and loading history

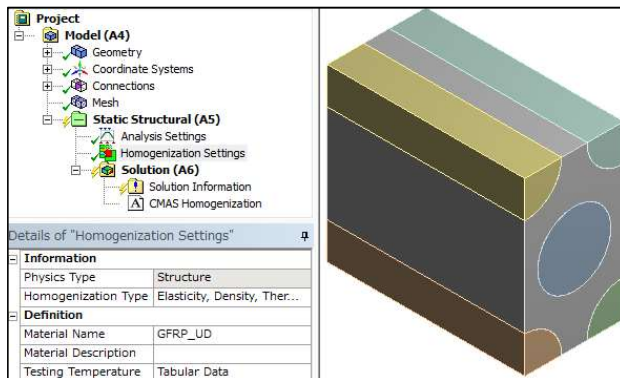


Material Designer vs. Multiscale.Sim

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Material Designer released from 2019
(SpaceClaim GUI)



Multiscale.Sim released from 2007
(Mechanical GUI)

Homogenization analysis tool is made by broadly two features which are model creation and homogenization analysis.

Feature comparison between two tools (as of Aug. 28, 2019)

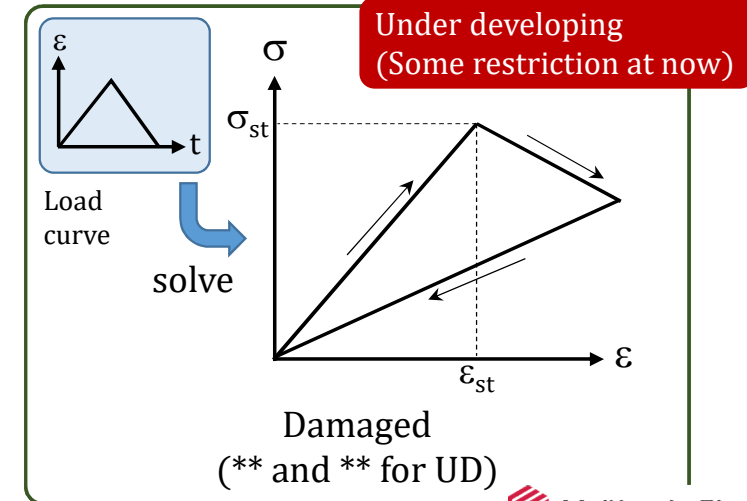
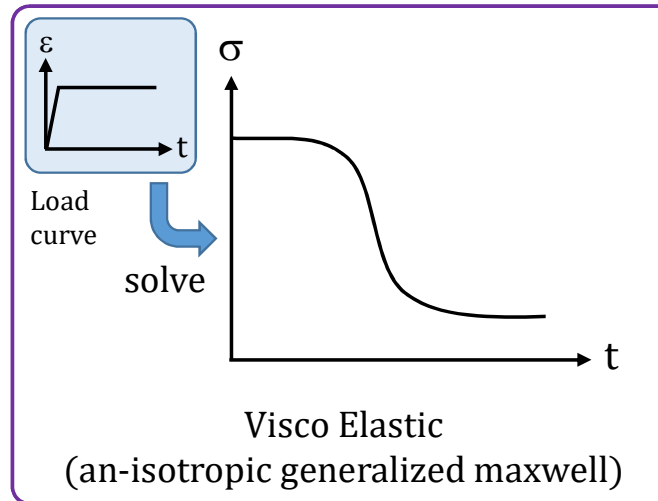
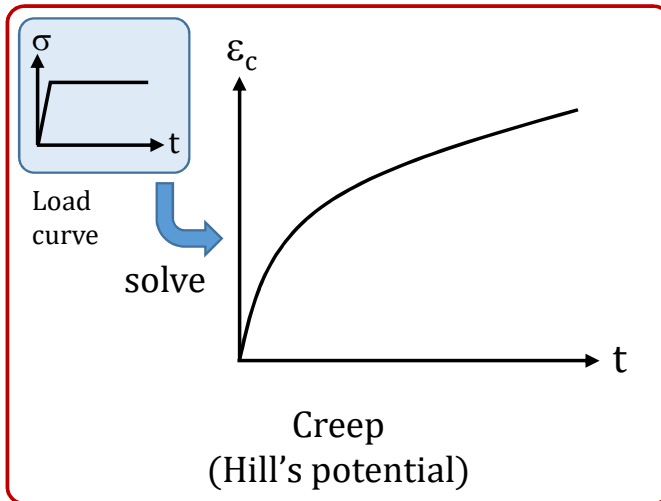
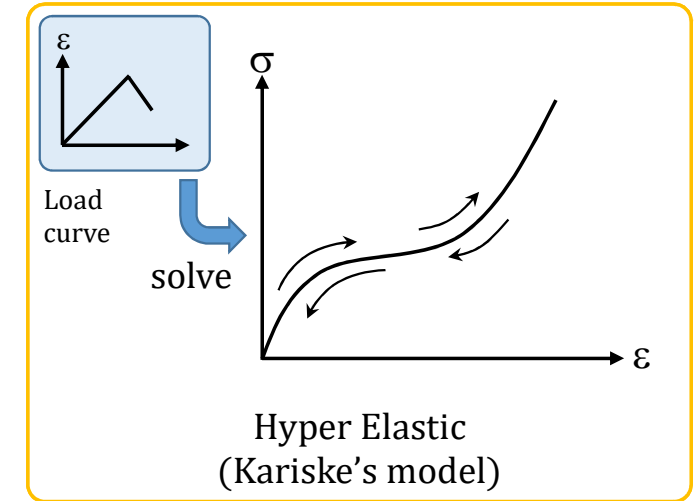
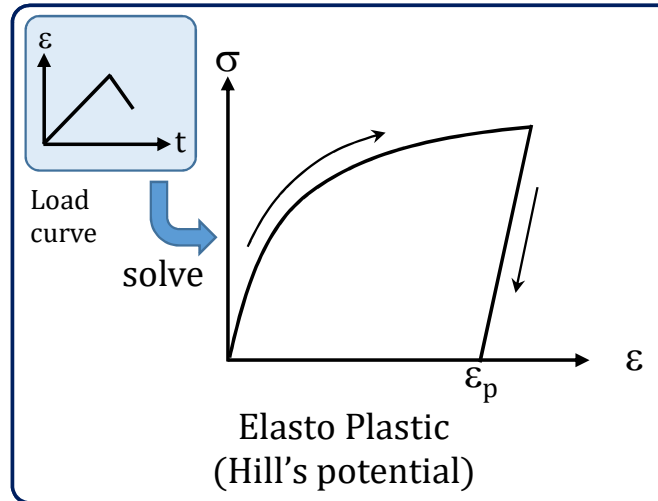
| Features | | Material Designer | Multiscale.Sim |
|--------------------------|--|-----------------------------|------------------------------|
| GUI | | SpaceClaim | Mechanical |
| Micro model creation | | 5 types | 17 types (Design Modeler) |
| License to use | | ANSYS Mechanical Enterprise | Multiscale.Sim |
| Linear Homogenization | Elasticity | ✓ | ✓ |
| | Thermal expans. | ✓ | ✓ |
| | Integrated section | | ✓ |
| | Thermal conduct. | ✓ | ✓ |
| | Seepage coeff. | | ✓ |
| | Permeability for Electric and Magnetic | | ✓ |
| Nonlinear Homogenization | Next slides for detail | | ✓ |
| Localization | | | ✓ |

Supported Material Behavior in Multiscale.Sim

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Nonlinear homogenization features

- Numerical Material testing
 - Any deformation mode
 - Any loading history
- Curve fitting
 - Original optimization algorithm (Tuned for each material models)



Purpose

Identification equivalent material constants for

- Orthotropic elasticity
- Coefficient of thermal expansion
- Density

Analysis Model

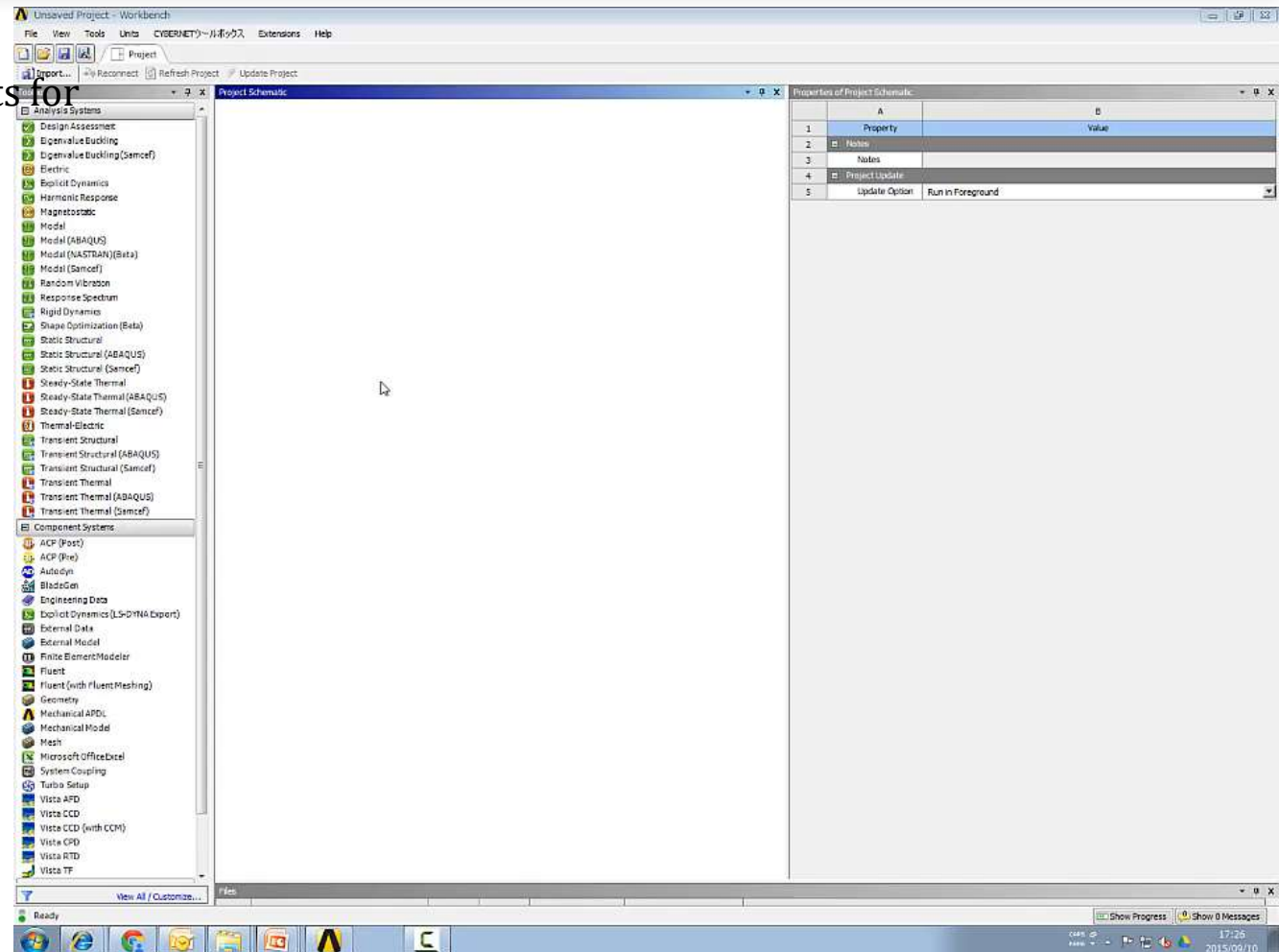
- SiC matrix & Aluminum filler
- Spherical filler dispersed in SiC

Material Type

- SiC : Pure Elastic
- Aluminum : Pure Elastic

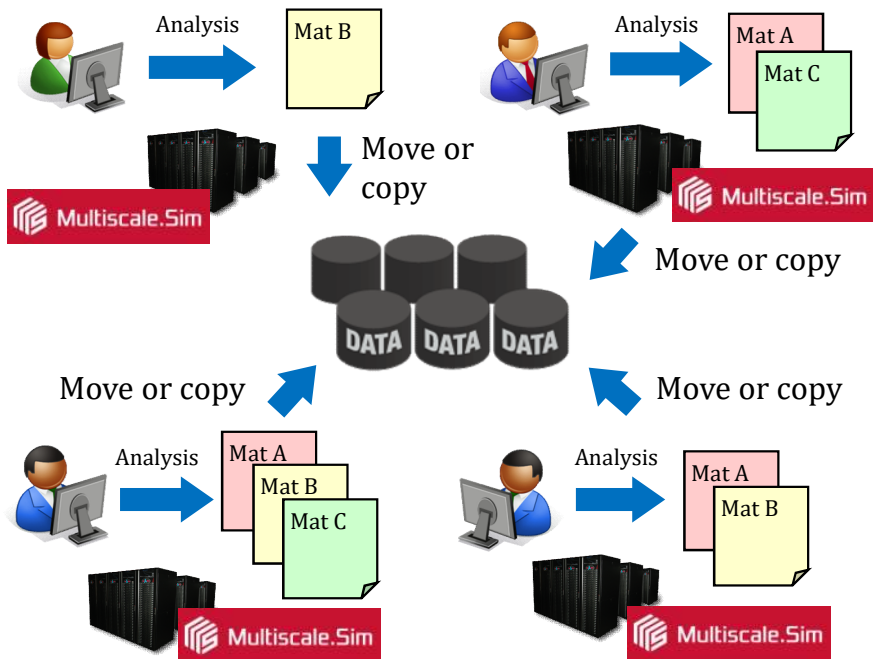
Operational Procedure

- Create Analysis System
- Creating microstructure
- Assigning material properties & Meshing
- Insert linear homogenization objects
- Confirmation results



Homogenization analysis in SPDM system
(SPDM : Simulation Process and Data Management)

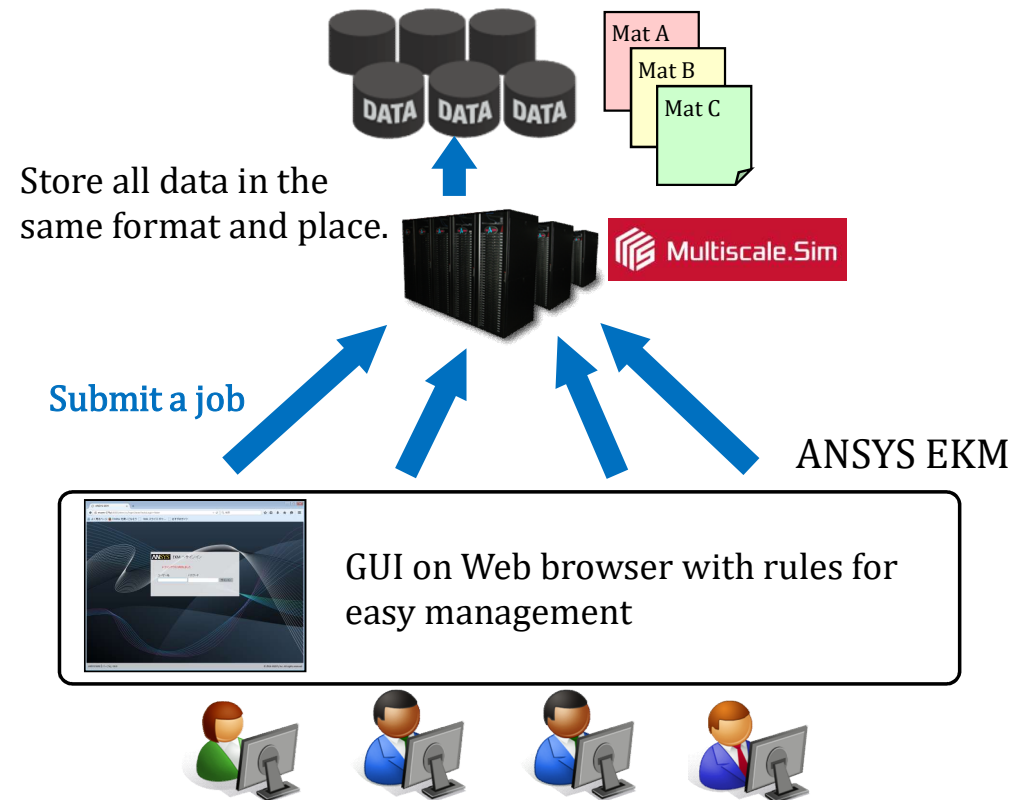
Conventional process

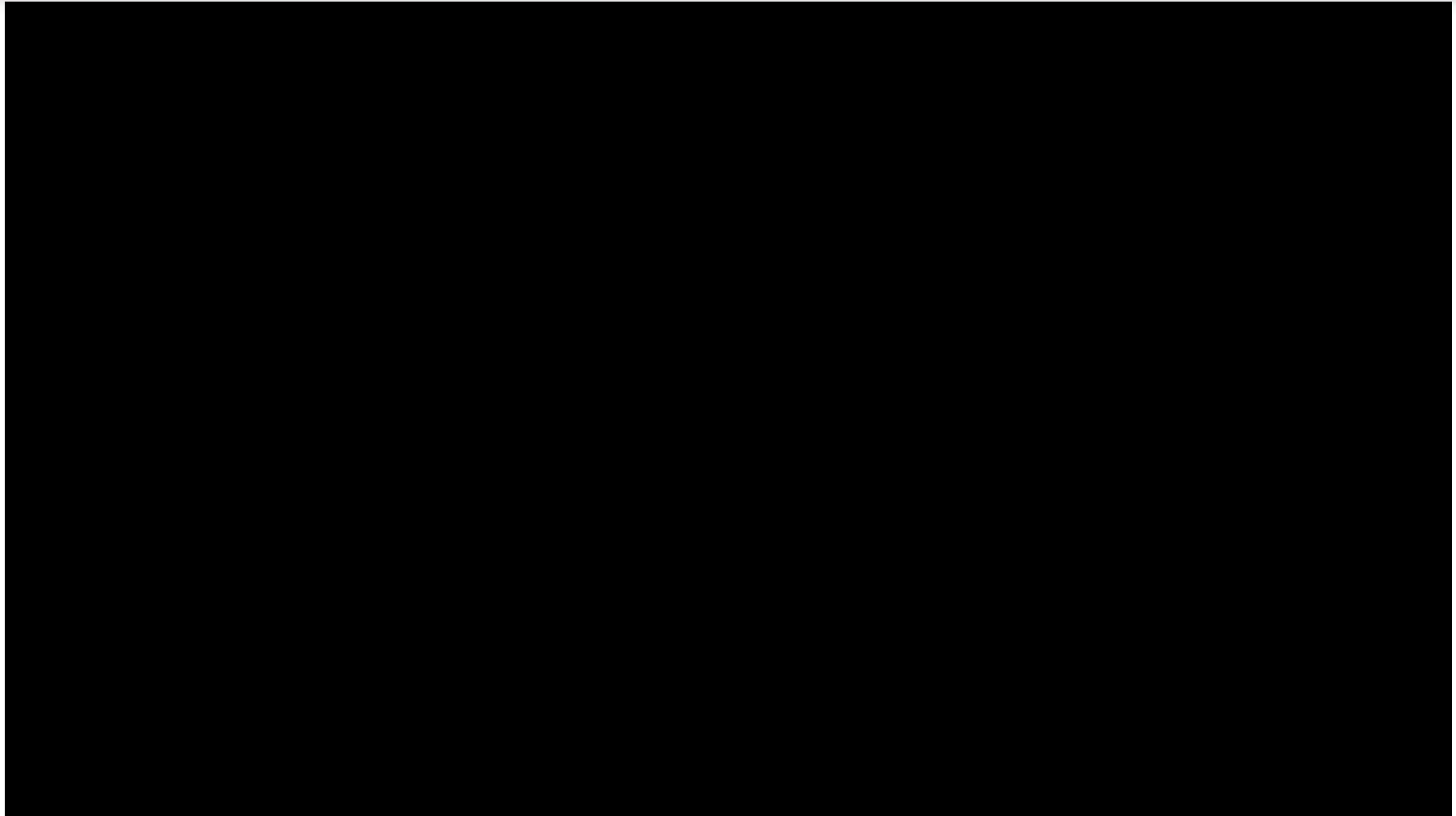


Demerit

- Duplication of data
- Lack of unity (spelling inconsistency)
- Different information although same name
- Unknown source

SPDM process

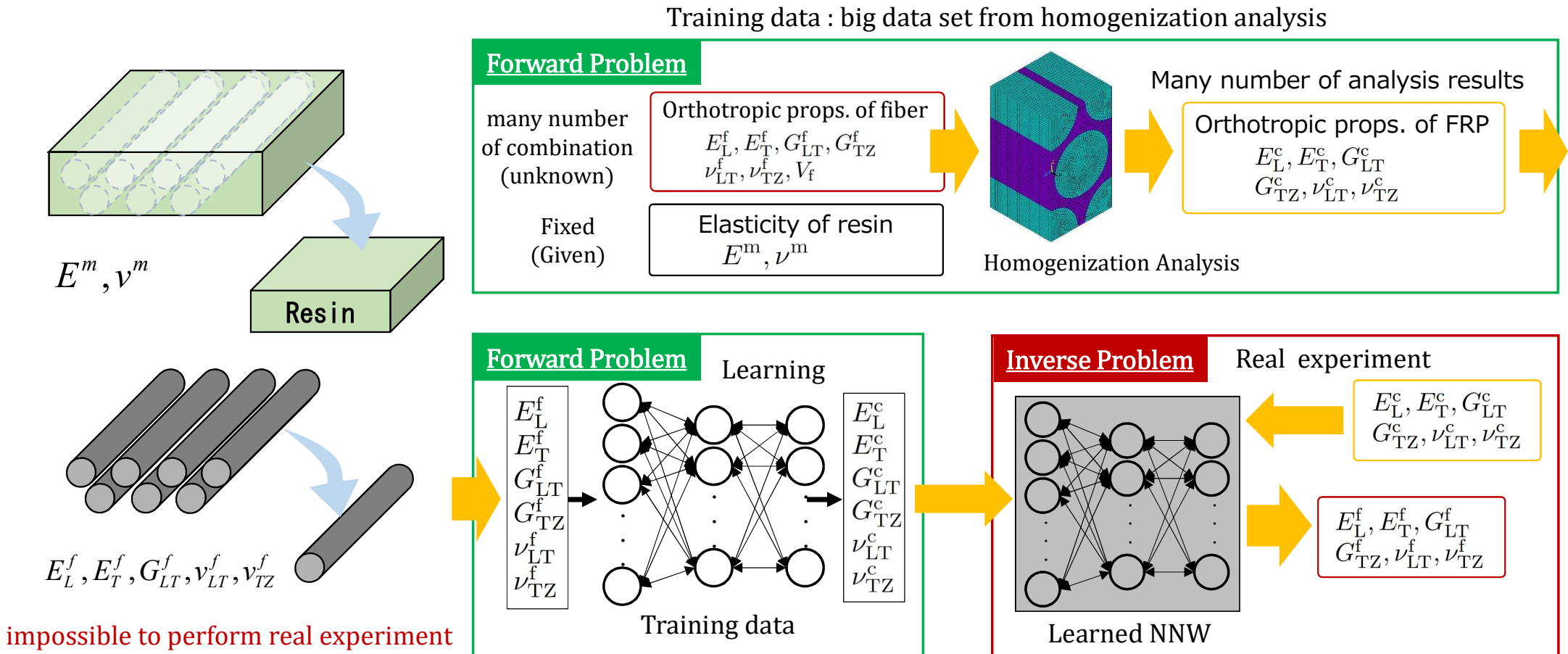




Analysis Examples

How to prepare material constants for input data

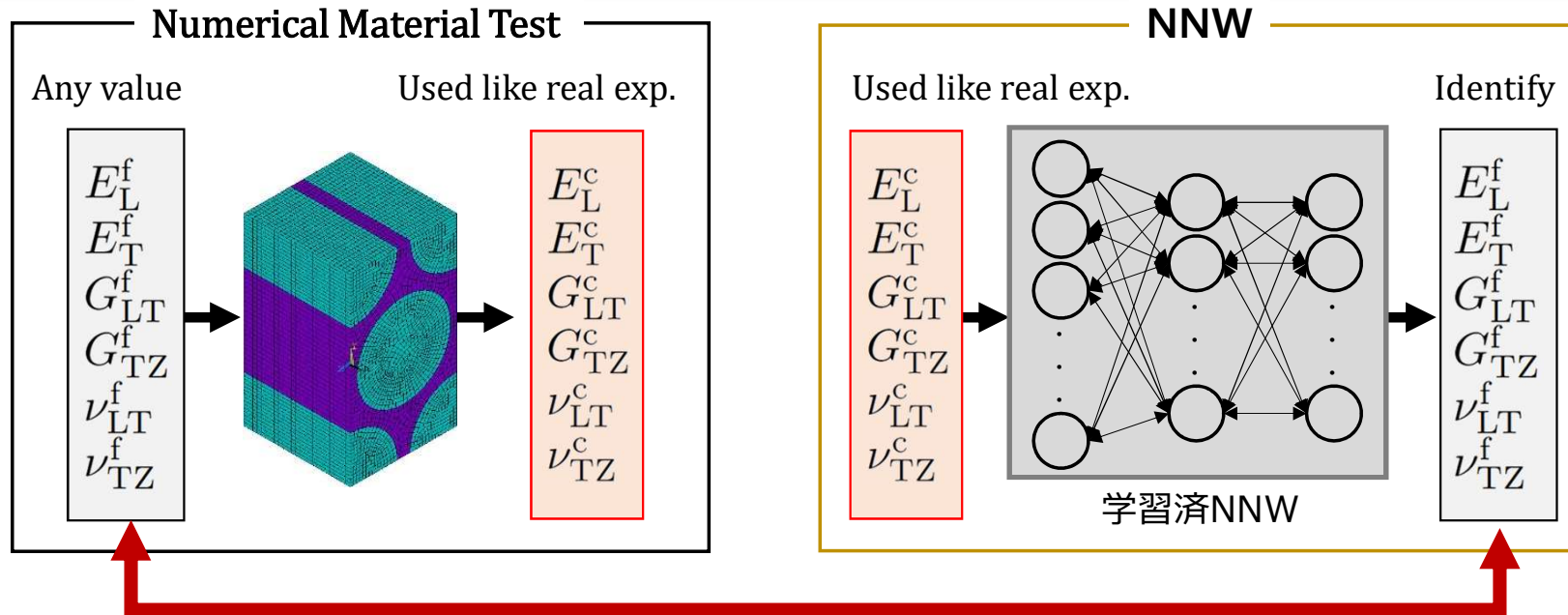
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Reference) S. Tsuchida, N. Hirayama, Y. Ishibashi, K. Yamamoto, K. Terada, Identification of orthotropic elastic constants for carbon fiber, Composite Symposium in Japan (2018)

How to prepare material constants for input data

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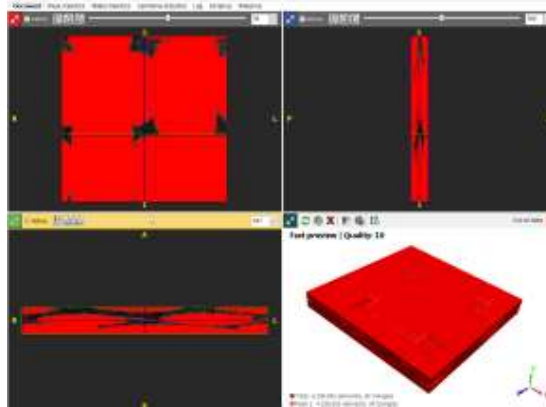
| Props. | Unit | Data | NNW | Error rate [%] |
|--------------|------|-------|-------|----------------|
| E_L^f | GPa | 237.5 | 239.1 | 0.67 |
| E_T^f | GPa | 16.5 | 16.90 | 2.30 |
| G_{LT}^f | GPa | 9.5 | 9.40 | 1.05 |
| ν_{LT}^f | - | 0.33 | 0.33 | 0.00 |
| ν_{TZ}^f | - | 0.50 | 0.51 | 2.00 |

Reference) S. Tsuchida, N. Hirayama, Y. Ishibashi, K. Yamamoto, K. Terada, Identification of orthotropic elastic constants for carbon fiber, Composite Symposium in Japan (2018)

Elasticity homogenization for woven CFRP

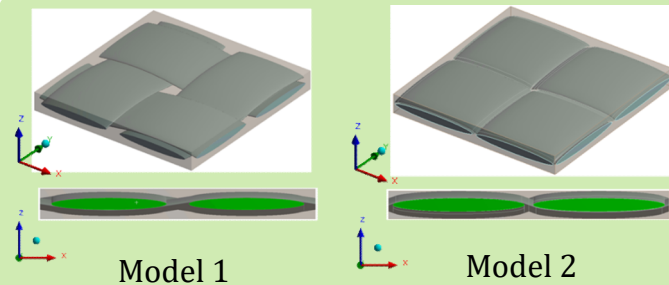
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Image analysis for identification of geometrical parameters

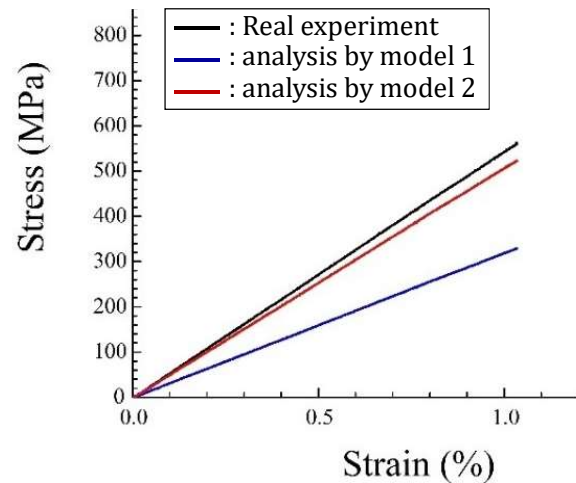


Simplware®

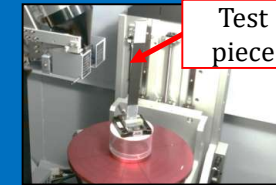
Image info. by DICOM data



- Model 1
 - Modeled woven shape by sine curve function
 - Volume fraction is not accurate
- Model 2
 - Modeled based on geometrical parameter as a result of X-ray observation



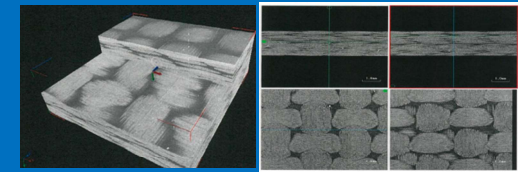
Validation



Test piece



inspeXio SMX-225CT FPD HR from Shimadzu corp.



Micro focus X-ray CT system



Autograph



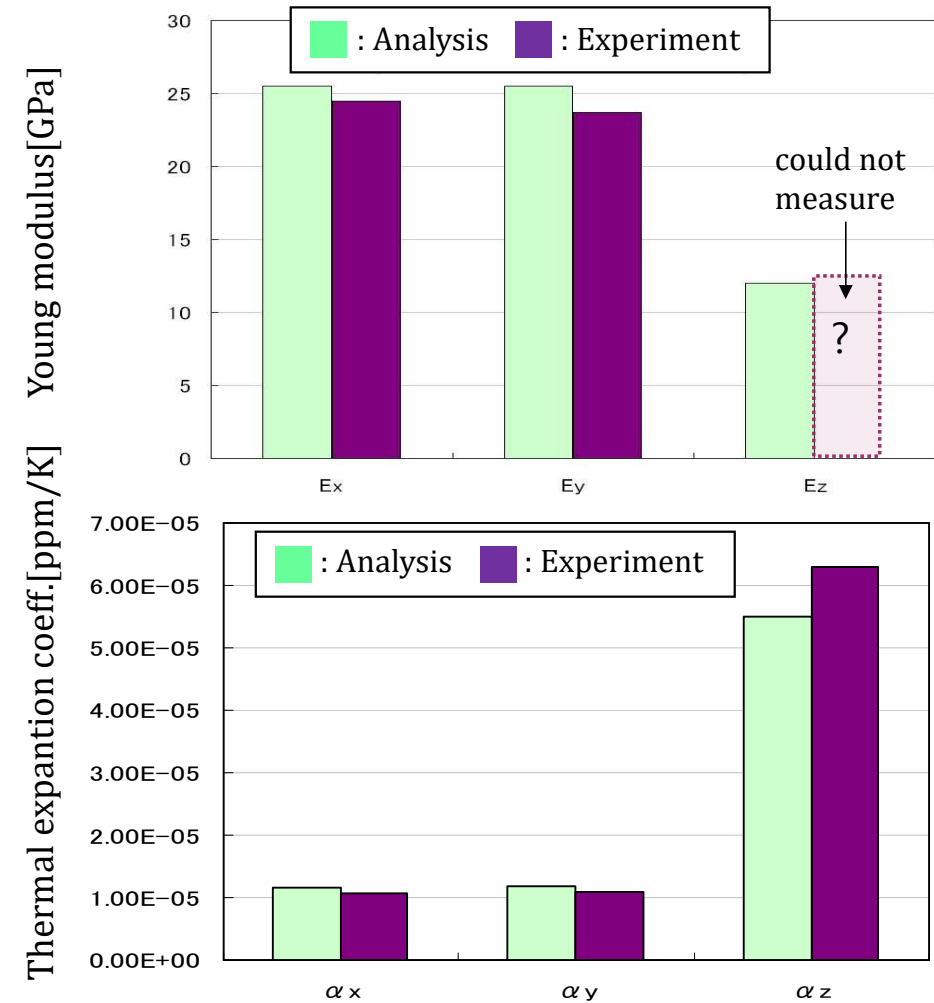
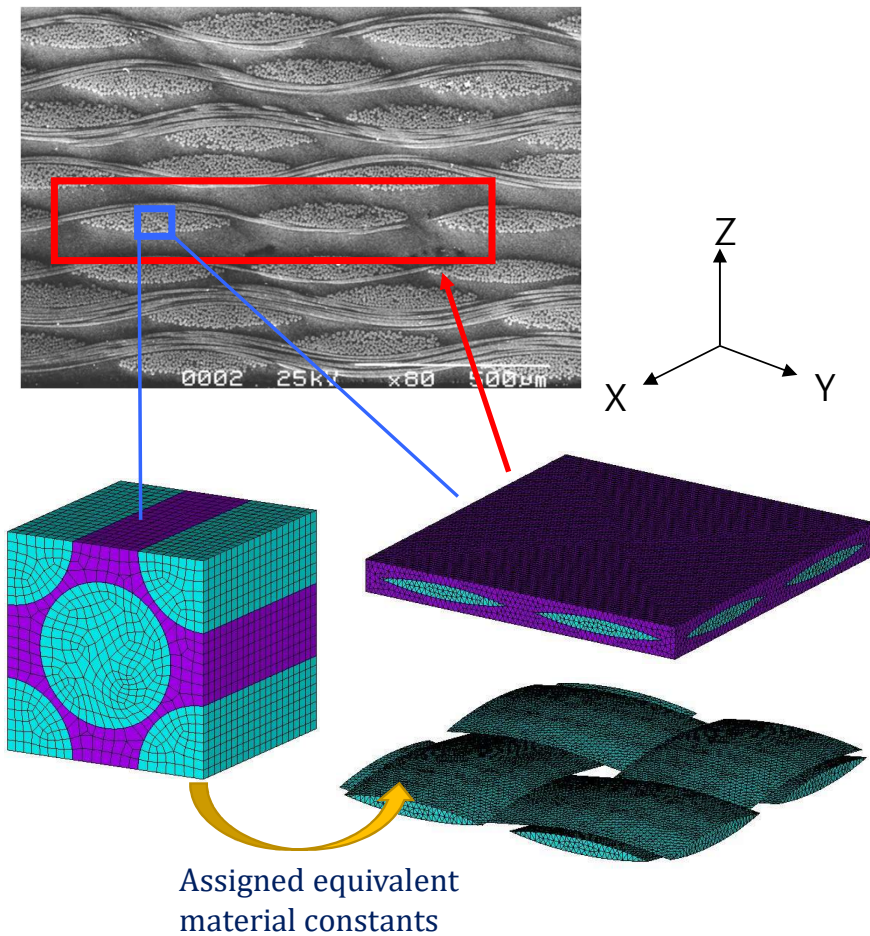
Precision universal tester

* Courtesy of Shimadzu corporation

FR4 (Glass fiber and Epoxy)

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- Grass cross used PCB and so on
- Evaluate elasticity and thermal expansion



Courtesy of NITTO BOSEKI Co., Ltd.

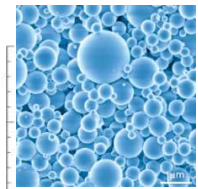
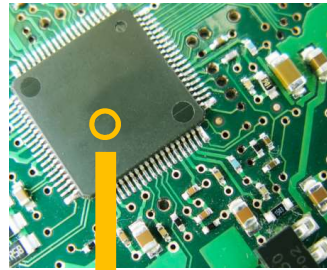
Filler dispersed composite

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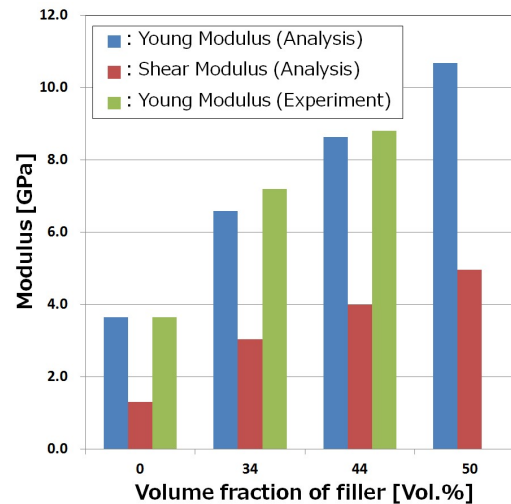
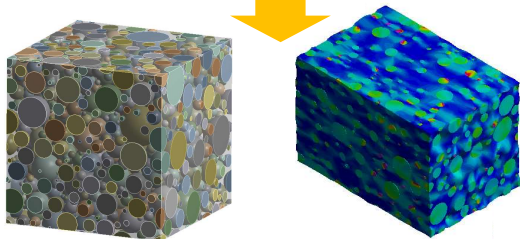
■ Sealing resin

Material property is controlled by fillers

- Model
 - SiC filler + Epoxy resin
 - Spherical filler
 - Consider size distribution
- Homogenization
 - Elastic



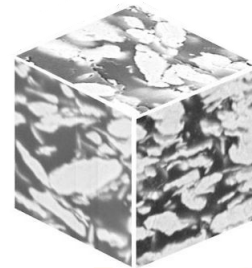
Size distribution



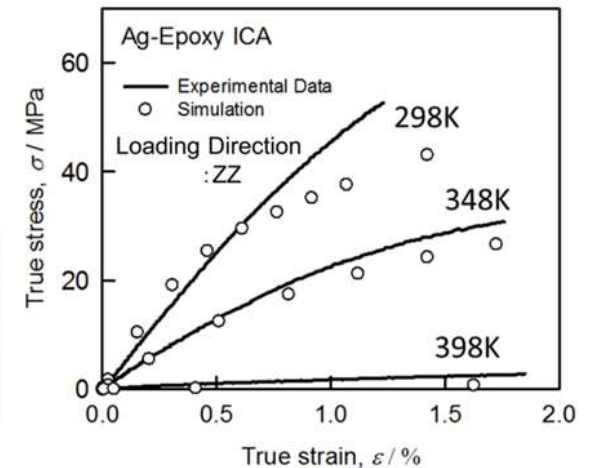
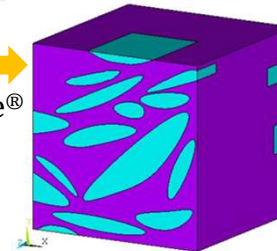
■ Conductive adhesive

Add Ag filler in matrix in order to achieve high conductivity

- Modeling
 - Ag filler + Epoxy resin
 - Complex filler's shape
 - Create by image base technique (Delete small parts)
- Homogenization
 - Elasto Plastic



Simplware®



Semiconductor Package

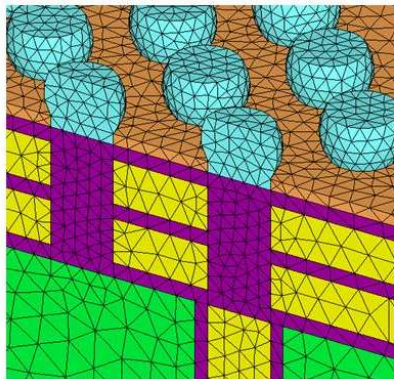
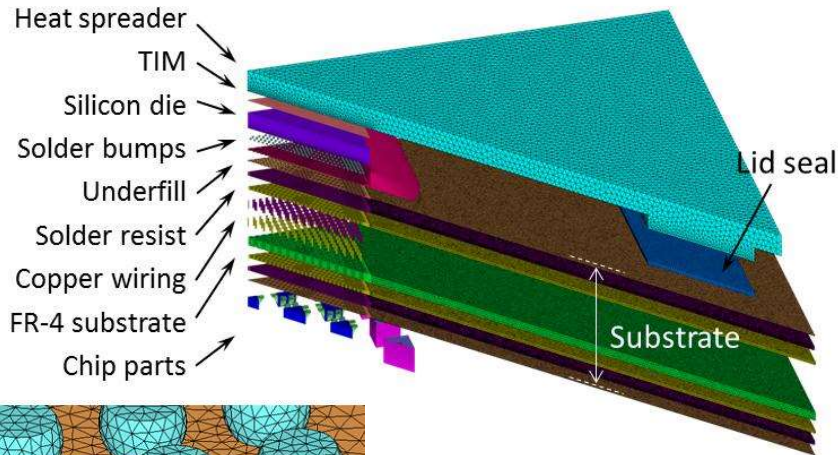
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➤ Model

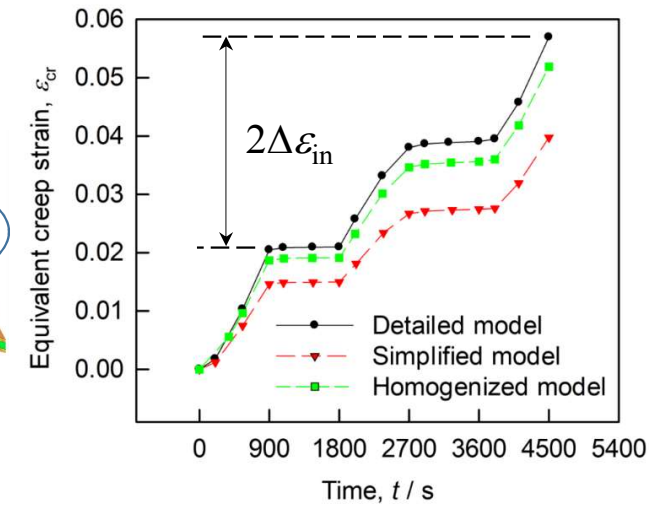
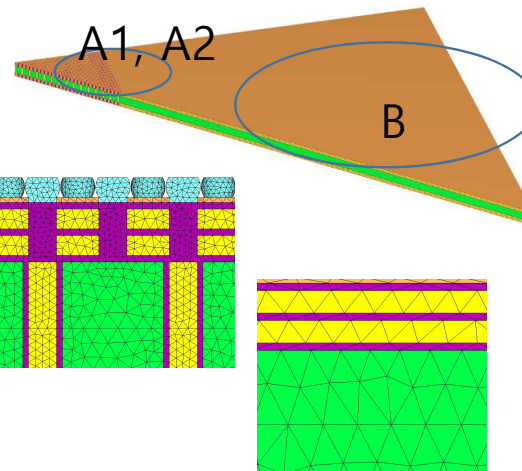
Considering Cu wiring structure under the bump.

➤ Purpose

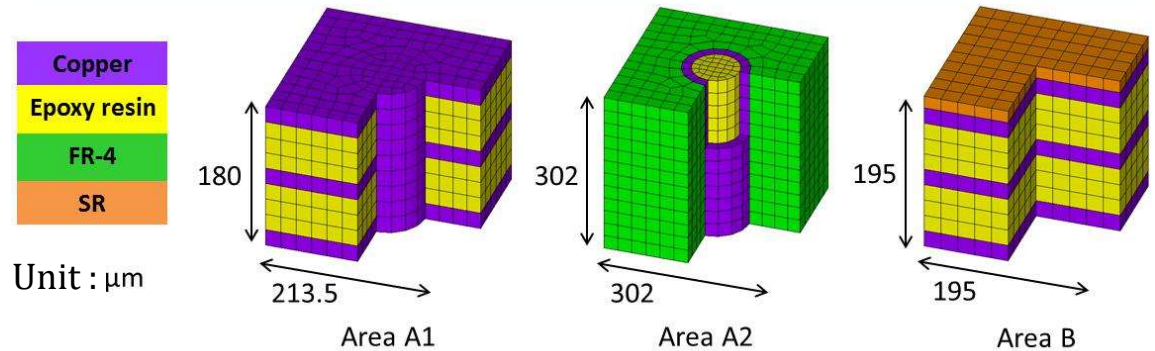
Analyze the effect of wiring structure on the strain in bump.



(About Ten million nodes)



Estimate anisotropic material constants at three point and replace homogenized model.



PCB is multi material product made by many composite.
It is important to prepare it's an-isotropic material constants.

Multiscale analysis approach based on homogenization technique is quite effective.

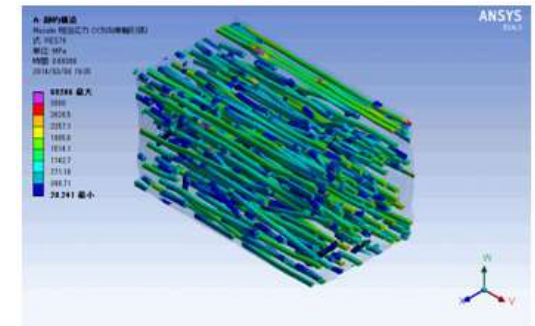
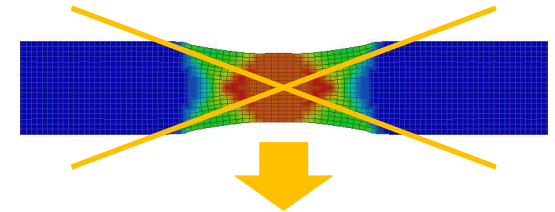
Difficulties of real experiments

Making all deformation modes for identification of an-isotropic properties
Taking a long time to perform.

Homogenization analysis solution

- Micro Model Creation
 - Many templates to create model automatically
- Numerical Material Test
 - Available for any deformation modes and loading history
- Curve fitting
 - Robust optimization algorithm to identify material constants

Good Material Database Leads Good Analysis



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Backup Slides

Simple examples for creep homogenization

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Multiscale creep analysis for lattice structure

Creep homogenization analysis

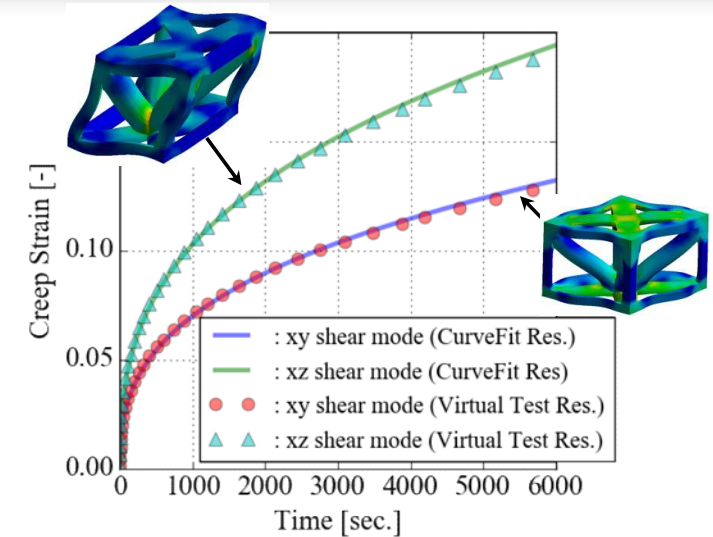
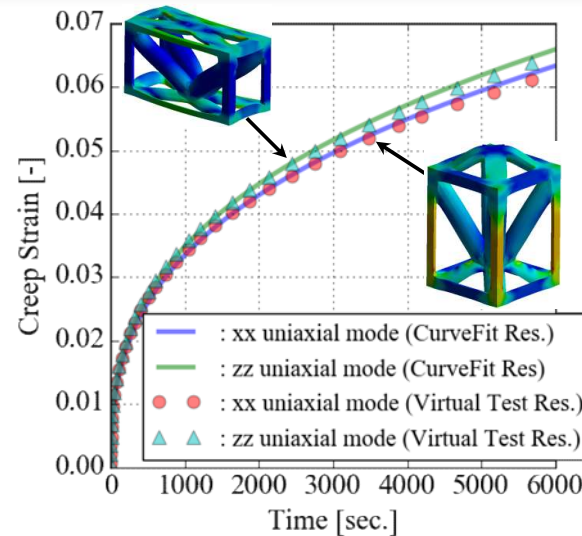
- Virtual test for 6 modes
 - xx,yy,zz uniaxial modes
 - xy,yz,xz pure shearing modes
- Curve fitting
 - PSO optimization
- Macroscopic constitutive law
 - Time hardening & Hill's potential

$$\dot{\epsilon}_{cr} = C_1 \sigma_{Hill}^{C_2} t^{C_3} \exp\left(-\frac{C_4}{T}\right)$$

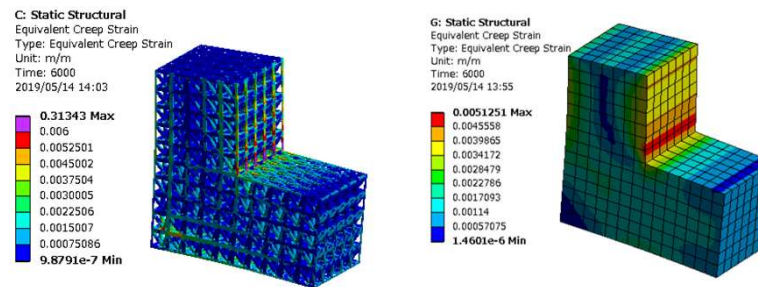
$$\sigma_{Hill} = \left\{ F(\sigma_{yy} - \sigma_{zz})^2 + G(\sigma_{zz} - \sigma_{xx})^2 + H(\sigma_{xx} - \sigma_{yy})^2 + 2N\tau_{xy}^2 + 2L\tau_{yz}^2 + 2M\tau_{xz}^2 \right\}^{1/2}$$

Macro scale analysis

- Direct model is used for validation
- Good correlation between 2 model.



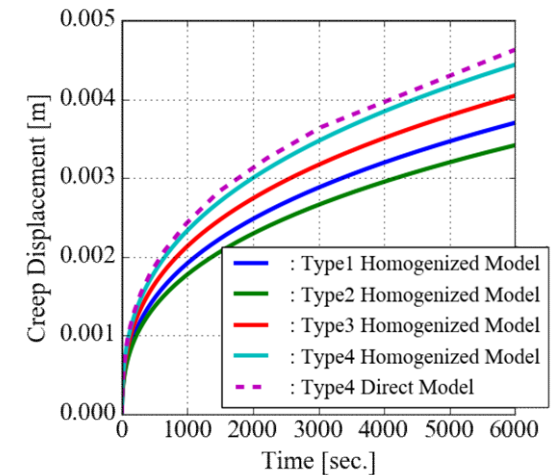
Creep behavior obtained virtual testing and the result of curve fitting



Direct Model
(Comput. Time=155 hours)

Homogenized Model
(Comput. Time=4 min)

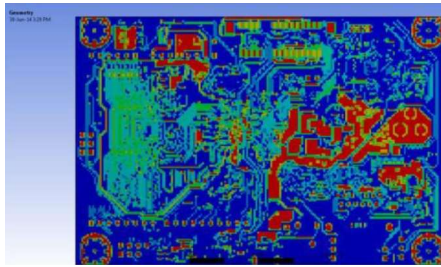
Faster 2300 times



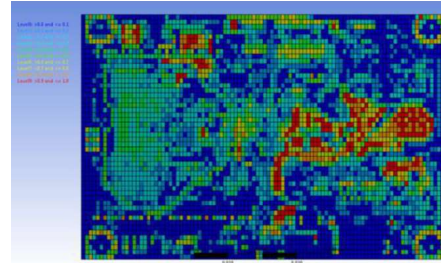
Homogenization for non-cyclic symmetry microstructure

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Trace Mapping



ECAD data



ECAD

➤ Mixing rule

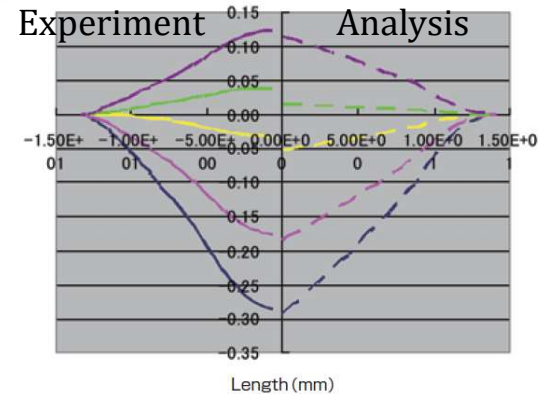
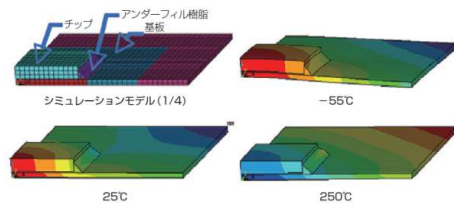
$$E_x^{\text{eff}}, E_y^{\text{eff}} = \frac{1}{\frac{f_s}{E_s} + \frac{f_u}{E_u} - \frac{f_s f_u (\nu_s E_u - \nu_u E_s)^2}{E_s E_u (f_s E_s - f_u E_u)}}$$

$$E_z^{\text{eff}} = f_s E_s + f_u E_u \quad \nu^{\text{eff}} = f_s \nu_s + f_u \nu_u$$

$$\alpha_z^{\text{eff}} = \frac{f_s E_s \alpha_s + f_u E_u \alpha_u}{f_s E_s + f_u E_u}$$

$$\alpha_x^{\text{eff}}, \alpha_y^{\text{eff}} = (1 + \nu_u) + \alpha_u f_u + (1 + \nu_s) \alpha_s f_s - \alpha_z^{\text{eff}} \nu^{\text{eff}}$$

- Material property
 - Board : homogenized anisotropic CTE at 9 regions
 - UF : visco elastic property of UF
- Real experiment
 - DIC technique



— -55°C — 25°C — 125°C — 175°C — 250°C
 — -55°C — 25°C — 125°C — 175°C — 250°C

